

APPLICATION NO. 10/642545

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CLMPTO

Claims 1-20 (cancelled)

Claim 21 (new). A configuration for connecting to electrical contacts of a printed circuit board, the configuration comprising:

a package having a base plate extending in a plane;

at least two terminal pins protruding perpendicularly from said base plate of said package, at least one of said terminal pins being a high-frequency terminal pin for transmitting a high-frequency signal;

a flexible conductor configuration including a plurality of interconnects, said conductor configuration for providing an electrical connection between said terminal pins protruding from said package and the electrical contacts of the printed circuit board;

said conductor configuration including a plurality of contact regions for electrically connecting each of said plurality of interconnects to a respective one of said

terminal pins and to a respective one of the electrical contacts of the printed circuit board;

said conductor configuration including at least one region lying in a plane aligned substantially perpendicularly to said plane of said base plate; and

said region of said conductor configuration providing a connection to said high-frequency terminal pin.

Claim 22 (new). The configuration according to claim 21, wherein:

said terminal pins extend in an axial direction;

said plurality of contact regions include an elongate contact region that is connected to said high-frequency terminal pin; and

said elongate contact region extends along said axial direction of said terminal pins.

Claim 23 (new). The configuration according to 21, wherein:

said conductor configuration includes a first part and a second part that is movable in relation to said first part;

said region of said conductor configuration is formed by said first part of said conductor configuration; and

said second part of said conductor configuration includes a plurality of interconnects for low-frequency signals.

Claim 24 (new). The configuration according to claim 23, further comprising:

two high-frequency terminal pins for transmitting high-frequency signals, said two high-frequency terminal pins being ones of said at least two terminal pins;

said first part of said conductor configuration having two contact regions contacting said two high-frequency terminal pins.

Claim 25 (new). The configuration according to claim 23, further comprising:

at least one contacting element protruding perpendicularly from said base plate of said package;

said base plate of said package formed in an electrically conducting manner; and

said first part of said conductor configuration having a contact region connected to a reference potential and to said contacting element.

Claim 26 (new). The configuration according to claim 25, further comprising:

a contacting plate protruding perpendicularly from said base plate; and

two high-frequency terminal pins for transmitting high-frequency signals, said two high-frequency terminal pins being ones of said at least two terminal pins;

said first part of said conductor configuration having two contact regions contacting said two high-frequency terminal pins;

said conductor configuration having a first side configured with said contact region connected to the reference potential and to said contacting element;

said conductor configuration having a second side configured with said two contact regions contacting said two high-frequency terminal pins;

said second side of said conductor configuration being opposite said first side of said conductor configuration; and

said conductor configuration having a region adjacent said base plate in which said first part of said conductor configuration runs between at least one of said two high-frequency terminal pins and said contacting plate.

Claim 27 (new). The configuration according to claim 23, wherein:

said conductor configuration has a common end region for contacting the printed circuit board; and

said first part of said conductor configuration and said second part of said conductor configuration are bent

differently towards said package, starting from said common end region.

Claim 28 (new). The configuration according to claim 27, wherein:

said first part of said conductor configuration has two sides;

said second part of said conductor configuration includes two bent lateral arms having ends;

each one of said two arms runs along a respective one of said two sides of said first part of said conductor configuration;

said second part of said conductor configuration includes a transverse region running substantially perpendicularly to said two arms and connecting said ends of said two arms;

said at least two terminal pins includes further terminal pins; and

said transverse region includes a plurality of contact regions for contacting said further terminal pins.

Claim 29 (new). The configuration according to claim 28, wherein said transverse region of said conductor configuration is oriented parallel to said base plate.

Claim 30 (new). The configuration according to claim 28, further comprising:

a thermistor pressed elastically against said base plate;

said transverse region of said conductor configuration having a side facing said base plate; and

said thermistor configured on said transverse region of said conductor configuration on said side facing said base plate.

Claim 31 (new). The configuration according to claim 28, wherein said two arms of said second part are bent in a U-shaped manner.

Claim 32 (new). The configuration according to claim 23, wherein said second part of said conductor configuration

includes a plurality of contact regions formed as via holes.

Claim 33 (new). The configuration according to claim 23, wherein:

said conductor configuration has a common end region for contacting the printed circuit board;

said first part of said conductor configuration and said second part of said conductor configuration are bent differently towards said package, starting from said common end region;

said plurality of interconnects of said second part have a length; and

said first part of said conductor configuration has a plurality of interconnects with a length being shorter than said length of said plurality of interconnects of said second part.

Claim 34 (new). The configuration according to claim 21, wherein:



said conductor configuration has a surface;

said conductor configuration is planar; and

one of said plurality of contact regions is an elongate contact pad formed on said surface of said conductor configuration and is connected to said high-frequency terminal pin.

Claim 35 (new). The configuration according to claim 21, wherein said plurality of contact regions are soldered to said terminal pins.

CLAIM 36-40 (CANCELLED)